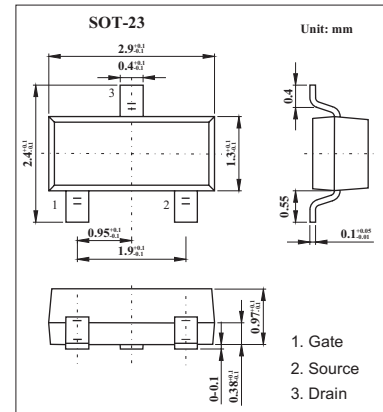
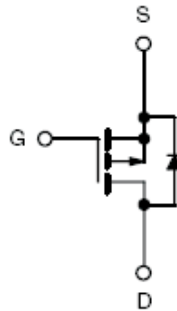
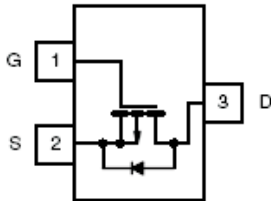


P-Channel 12-V (D-S) MOSFET

KI2337DS

■ Features

- TrenchFET Power MOSFET

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	5 sec	Unit
Drain-Source Voltage	V_{DS}	-80	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_J=150^\circ\text{C}$) $T_C=25^\circ\text{C}$ $T_C=70^\circ\text{C}$	I_D	-2.2 -1.75	A
Continuous Drain Current ($T_J=150^\circ\text{C}$) *1,2 $T_A=25^\circ\text{C}$ $T_A=70^\circ\text{C}$	I_D	-1.2 -0.96	A
Pulsed Drain Current	I_{DM}	-7	A
Continuous Source Drain Diode Current $T_C=25^\circ\text{C}$	I_S	-2.1	
Continuous Source Drain Diode Current *1,2 $T_A=25^\circ\text{C}$	I_S	-0.63	
Avalanche Current $L = 0.1 \text{ mH}$	I_{AS}	11	mJ
Single-Pulse Avalanche Energy $L = 0.1 \text{ mH}$	E_{AS}	6.0	
Power Dissipation $T_C=25^\circ\text{C}$ $T_C=70^\circ\text{C}$	P_D	2.5 1.6	W
Power Dissipation *1,2 $T_A=25^\circ\text{C}$ $T_A=70^\circ\text{C}$	P_D	0.76 0.48	
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to +150	$^\circ\text{C}$
Soldering Recommendations (Peak Temperature)*3		260	$^\circ\text{C}$

*1 Surface mounted on 1" x 1" FR4 Board.

*2 $t = 10 \text{ sec}$

*3 Maximum under steady state conditions is $166^\circ\text{C}/\text{W}$.

KI2337DS

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = -250 μA	-80			V
VDS Temperature Coefficient	ΔV _{DS} /T _J	I _D = -250 μA		-35.8		mV/°C
VGS(th) Temperature Coefficient	ΔV _{GS(th)} /T _J			5.45		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 μA	-2		-4	V
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA
Zero Gate Voltage Drain Current	I _{BSS}	V _{DS} = -80V, V _{GS} = 0 V			-1	μA
		V _{DS} = -80 V, V _{GS} = 0 V, T _J = 55 °C			-10	
On-State Drain Current	I _{D(on)}	V _{DS} ≥ -5V, V _{GS} = -10V	-7			A
Drain-Source On-State Resistance *	r _{DS(on)}	V _{GS} = -10V, I _D = -1.2A		0.216	0.270	Ω
		V _{GS} = -6V, I _D = -1.1 A		0.242	0.303	
Forward Transconductance *	g _{fs}	V _{DS} = -15 V, I _D = -1.2A		4.3		S
Input Capacitance	C _{iss}	V _{DS} = -40 V, V _{GS} = 0, f = 1 MHz		500		pF
Output Capacitance	C _{oss}			40		
Reverse Transfer Capacitance	C _{rss}			25		
Total Gate Charge	Q _g	V _{DS} = -40 V, V _{GS} = -10 V, I _D = -1.2 A		11	17.0	
Total Gate Charge	Q _g	V _{DS} = -40V, V _{GS} = -6 V, I _D = -1.2A		7	11.0	nC
Gate-Source Charge	Q _{gs}			2.1		
Gate-Drain Charge	Q _{gd}			3.2		
Gate Resistance	R _g	f = 1 MHz		4.8		Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = -40V, R _L = 42 Ω, I _D = -0.96A, V _{GEN} = -10V, R _G = 1 Ω		10	15	ns
Rise Time	t _r			15	23	
Turn-Off Delay Time	t _{d(off)}			20	30	
Fall Time	t _f			15	23	
Turn-On Delay Time	t _{d(on)}	V _{DD} = -40V, R _L = 42 Ω, I _D = -0.96A, V _{GEN} = -6V, R _G = 1 Ω		15	23	ns
Rise Time	t _r			18	27	
Turn-Off Delay Time	t _{d(off)}			20	30	
Fall Time	t _f			12	18	
Continuous Source-Drain Diode Current	I _S	T _C = 25°C			-2.1	A
Pulse Diode Forward Current*	I _{SM}				-7	
Body Diode Voltage	V _S	I _S = 0.63 A		-0.8	-1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = 0.63 A, di/dt = 100 A/μs, T _J = 25°C		30	45	ns
Body Diode Reverse Recovery Charge	Q _{rr}			45	70	nC
Reverse Recovery Fall Time	t _a			25		ns
Reverse Recovery Rise Time	t _b			5		

* Pulse test: PW ≤ 300 μs duty cycle ≤ 2%.

■ Marking

Marking	E7
---------	----